



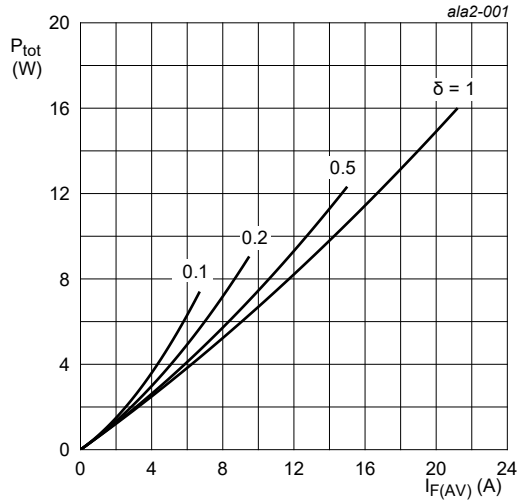


## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

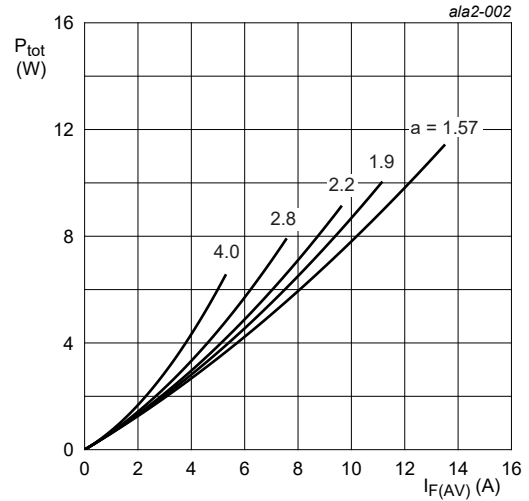
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}$	repetitive peak reverse voltage		-	100	V
$V_{RWM}$	limiting crest working reverse voltage		-	100	V
$V_R$	limiting reverse voltage	DC	-	100	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $T_{mb} \leq 134$ °C; square-wave pulse; per diode; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	15	A
$I_{O(AV)}$	average output current	$\delta = 0.5$ ; $T_{mb} \leq 133$ °C; square-wave pulse; both diodes conducting	-	30	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode; <a href="#">Fig. 4</a>	-	330	A
		$t_p = 8.3$ ms; $T_{j(init)} = 25$ °C; sine-wave pulse; per diode	-	363	A
$T_{stg}$	storage temperature		-40	150	°C
$T_j$	junction temperature		-	150	°C



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 0.593 \text{ V}; R_s = 0.0076 \text{ } \Omega$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode**



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 0.593 \text{ V}; R_s = 0.0076 \text{ } \Omega$$

**Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values; per diode**

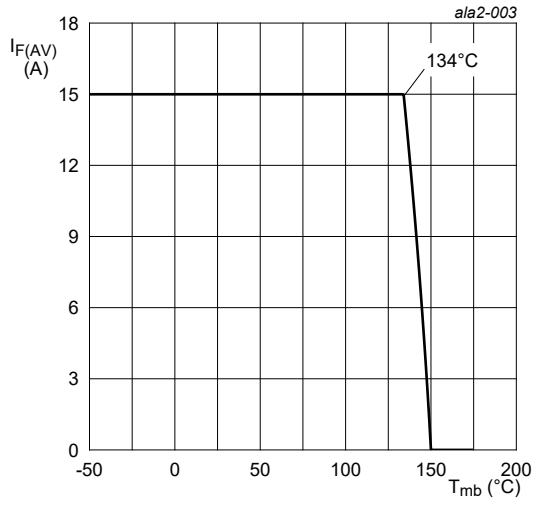


Fig. 3. Average forward current as a function of mounting base temperature; maximum values; per diode

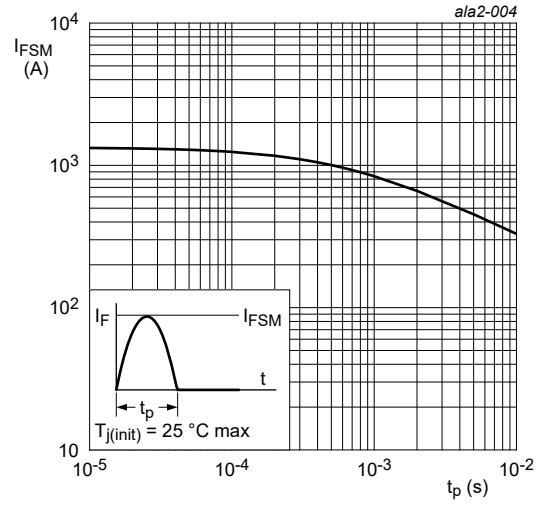


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

### 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	per diode; Fig. 5	-	-	1.3	K/W
		both diodes conducting	-	-	0.7	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	-	60	-	K/W

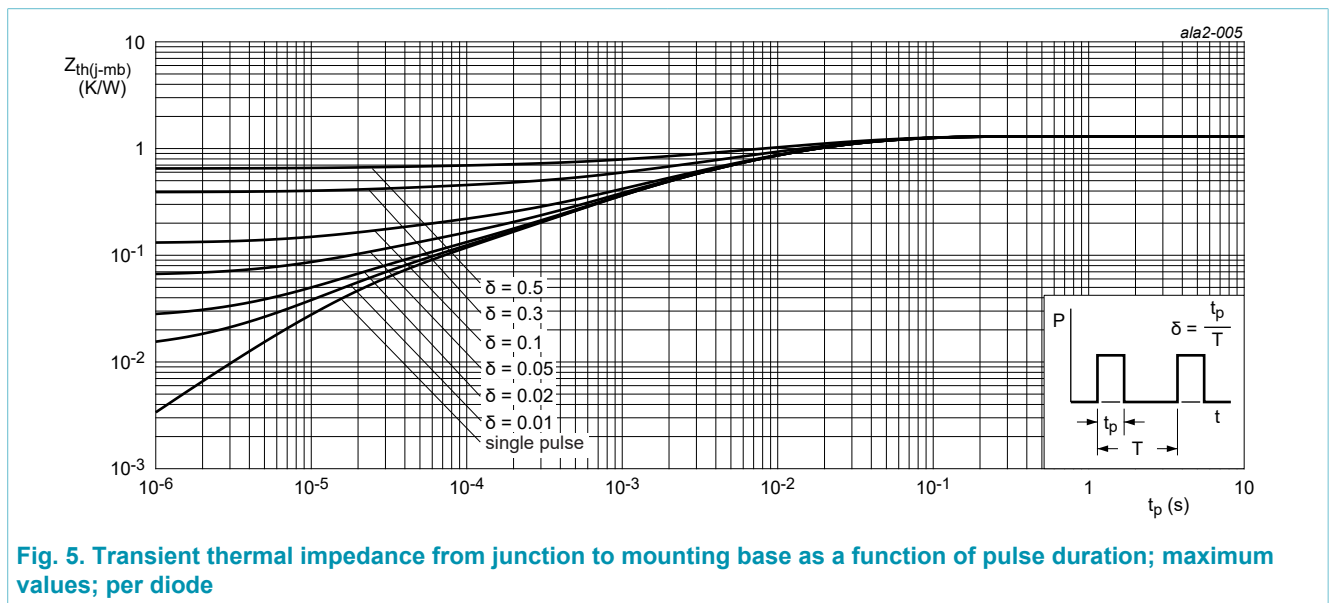
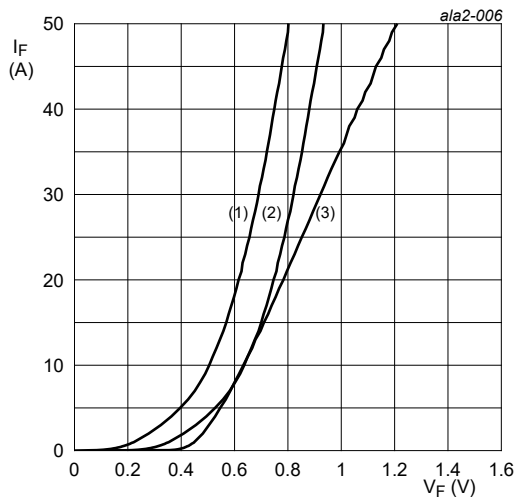


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration; maximum values; per diode

### 9. Characteristics

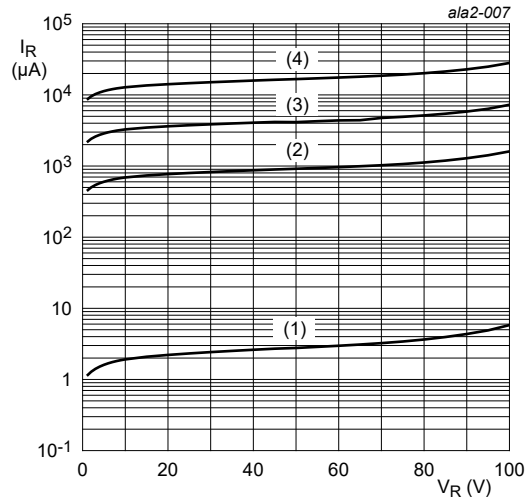
Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 5 A; T <sub>j</sub> = 25 °C; Fig. 6; per diode	-	0.48	0.55	V
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C; Fig. 6; per diode	-	0.41	0.48	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; Fig. 6; per diode	-	0.56	0.63	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 125 °C; Fig. 6; per diode	-	0.53	0.6	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 25 °C; Fig. 6; per diode	-	0.64	0.71	V
		I <sub>F</sub> = 15 A; T <sub>j</sub> = 125 °C; Fig. 6; per diode	-	0.6	0.67	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 100 V; T <sub>j</sub> = 25 °C; Fig. 7; Fig. 8; per diode	-	-	50	μA
		V <sub>R</sub> = 100 V; T <sub>j</sub> = 125 °C; Fig. 7; Fig. 8; per diode	-	-	30	mA



V<sub>o</sub> = 0.593 V; R<sub>s</sub> = 0.0076 Ω  
 (1) T<sub>j</sub> = 150 °C; typical values  
 (2) T<sub>j</sub> = 150 °C; maximum values  
 (3) T<sub>j</sub> = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage; per diode



(1) T<sub>j</sub> = 25 °C; typical values  
 (2) T<sub>j</sub> = 100 °C; typical values  
 (3) T<sub>j</sub> = 125 °C; typical values  
 (4) T<sub>j</sub> = 150 °C; typical values

Fig. 7. Reverse leakage current as a function of reverse voltage; per diode; typical values

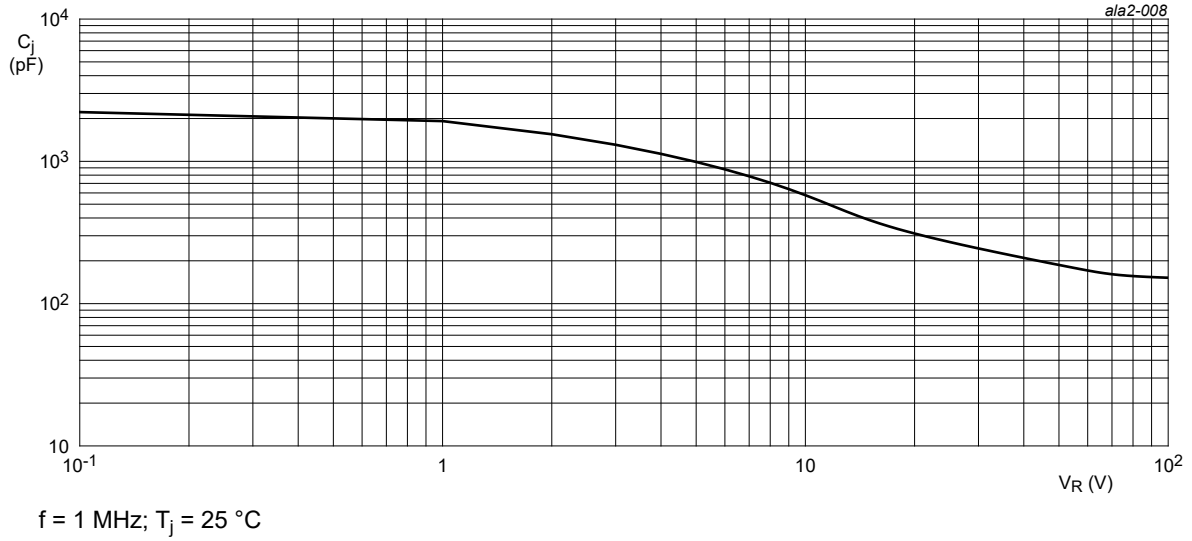
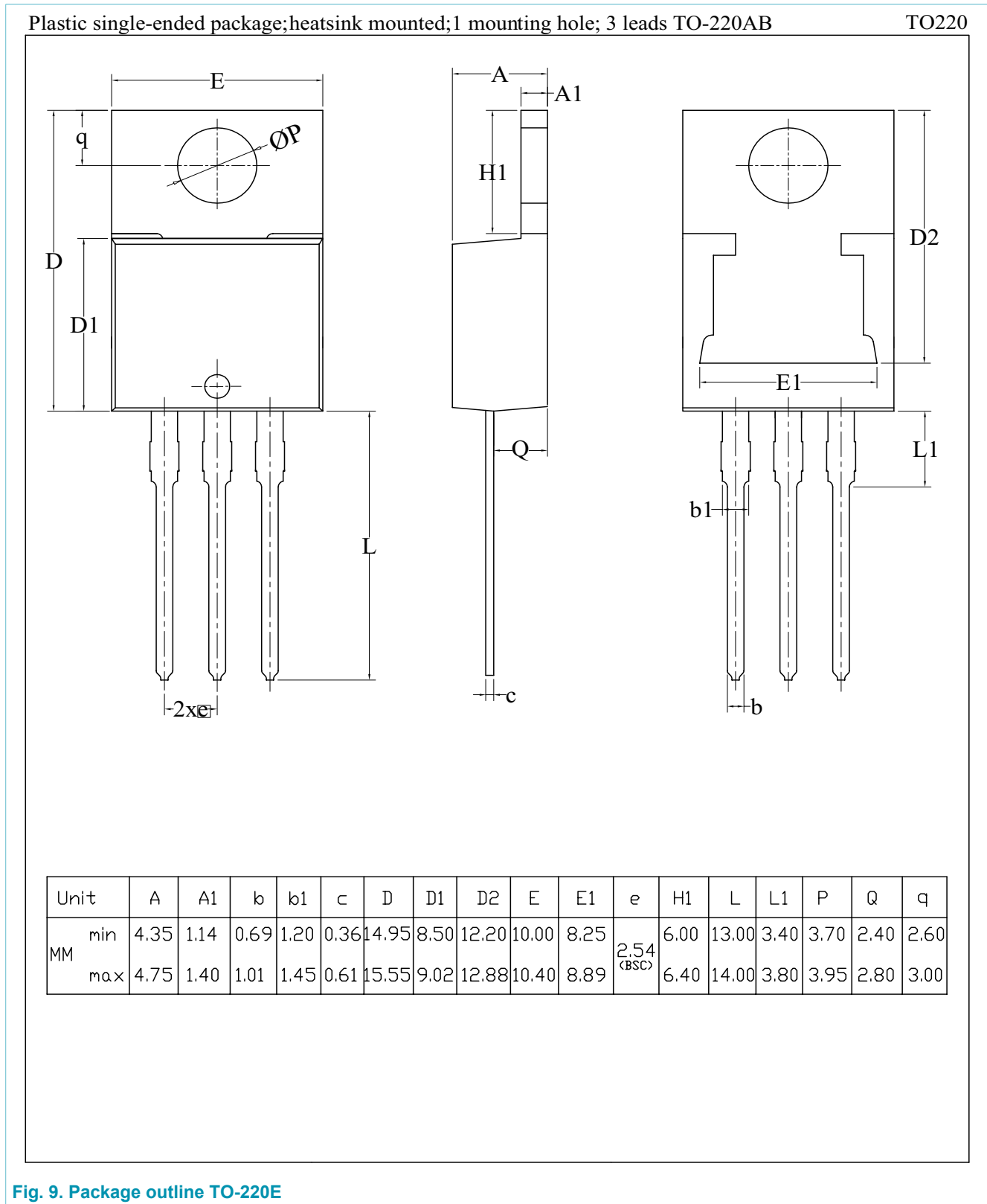


Fig. 8. Junction capacitance as a function of applied reverse voltage; per diode; typical values

### 10. Package outline





## 11. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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